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**General Description:**

Module shall be an encapsulated assembly, resistors, carbon shall be per mil-r-39008, resistors, metal film per mil-r-10509, resistors, wirewound per mil-r-93, diodes and transistors per mil-s-19500, microelectronic circuits from device families previously used in military applications, pins shall be solderable per mil-std-202, method 208, pins shall be brass per qq-b-626, composition 22, pin plating shall be electro-solder per mil-f-14072, m222, environmental conditions after encapsulation: shock per mil-std-202, method 213, test condition j, vibration per mil-std-202, method 201, 2.170 in. O/a lg, 1.535 in. O/a w, 1.240 in. O/a h

**Shelf Life:**

N/a

**Unit Of Measure:**

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**Demilitarization:**

Yes - demil/mli